



## Material Content Data Sheet



<b>Sales Product Name</b>		ICE3B0565J		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001054998						
<b>Package</b>		PG-DIP-8-9		<b>Weight*</b>		518.10 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.391	0.46	0.46	4615	4615
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.01		103	
	non noble metal	zinc	7440-66-6	0.213	0.04		412	
	non noble metal	iron	7439-89-6	4.266	0.82		8235	
wire	non noble metal	copper	7440-50-8	173.237	33.44	34.31	334368	343118
	noble metal	gold	7440-57-5	0.450	0.09	0.09	868	868
	encapsulation	organic material	carbon black	1333-86-4	1.311	0.25		2530
encapsulation	plastics	epoxy resin	-	38.015	7.34		73372	
	inorganic material	silicondioxide	60676-86-0	288.386	55.67	63.26	556618	632520
	leadfinish	non noble metal	tin	7440-31-5	7.496	1.45	1.45	14468
plating	noble metal	silver	7440-22-4	0.801	0.15	0.15	1546	1546
glue	plastics	epoxy resin	-	0.223	0.04		430	
	noble metal	silver	7440-22-4	1.261	0.24	0.28	2435	2865
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com